

**PATENT NUMBER and
ISSUE DATE**

U.S. UTILITY Patent Application

APPL NUM 10033114	FILING DATE 10/22/2001	CLASS 438	SUBCLASS 22	GAU 2812	EXAMINER <i>Garcia</i>
----------------------	---------------------------	--------------	----------------	-------------	---------------------------

****APPLICANTS:** Lee Tai-Peng; Jang Chuck;

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO M-11912 US
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	
Verified and Acknowledged Examiners's initials			
TITLE : Reduced thickness variation in a material layer deposited in narrow and wide integrated circuit trenches			

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH: ☐ DISK (CRF) ☐ CD-ROM
 (Attached in pocket on right inside flap)